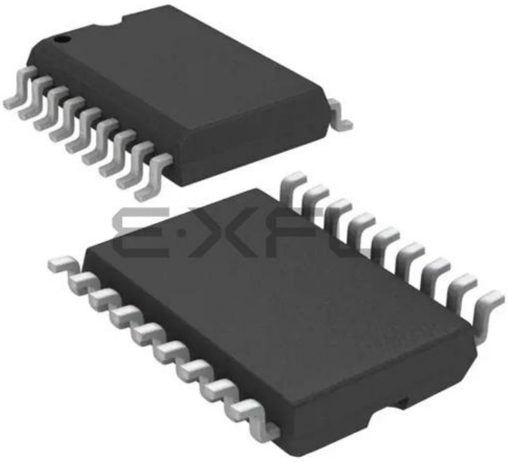
Microchip Technology - PIC16LCE625-04I/SO Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce625-04i-so

1.0 GENERAL DESCRIPTION

The PIC16CE62X are 18 and 20-Pin EPROM-based members of the versatile PIC® family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers with EEPROM data memory.

All PIC® microcontrollers employ an advanced RISC architecture. The PIC16CE62X family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single-cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CE62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16CE623 and PIC16CE624 have 96 bytes of RAM. The PIC16CE625 has 128 bytes of RAM. Each microcontroller contains a 128x8 EEPROM memory array for storing non-volatile information, such as calibration data or security codes. This memory has an endurance of 1,000,000 erase/write cycles and a retention of 40 plus years.

Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16CE62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16CE62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and reset.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock- up.

A UV-erasable CERDIP-packaged version is ideal for code development, while the cost-effective One-Time Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16CE62X mid-range microcontroller families.

A simplified block diagram of the PIC16CE62X is shown in Figure 3-1.

The PIC16CE62X series fits perfectly in applications ranging from multi-pocket battery chargers to low-power remote sensors. The EPROM technology makes customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high-performance, ease of use and I/O flexibility make the PIC16CE62X very versatile.

1.1 Development Support

The PIC16CE62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low-cost development programmer and a full-featured programmer. A “C” compiler is also available.

NOTES:

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CE62X family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CE62X uses a Harvard architecture in which program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched from the same memory. Separating program and data memory further allows instructions to be sized differently than 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (35) execute in a single-cycle (200 ns @ 20 MHz) except for program branches.

The table below lists program memory (EPROM), data memory (RAM) and non-volatile memory (EEPROM) for each PIC16CE62X device.

Device	Program Memory	RAM Data Memory	EEPROM Data Memory
PIC16CE623	512x14	96x8	128x8
PIC16CE624	1Kx14	96x8	128x8
PIC16CE625	2Kx14	128x8	128x8

The PIC16CE62X can directly or indirectly address its register files or data memory. All special function registers including the program counter are mapped in the data memory. The PIC16CE62X family has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of ‘special optimal situations’ make programming with the PIC16CE62X simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC16CE62X devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8 bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

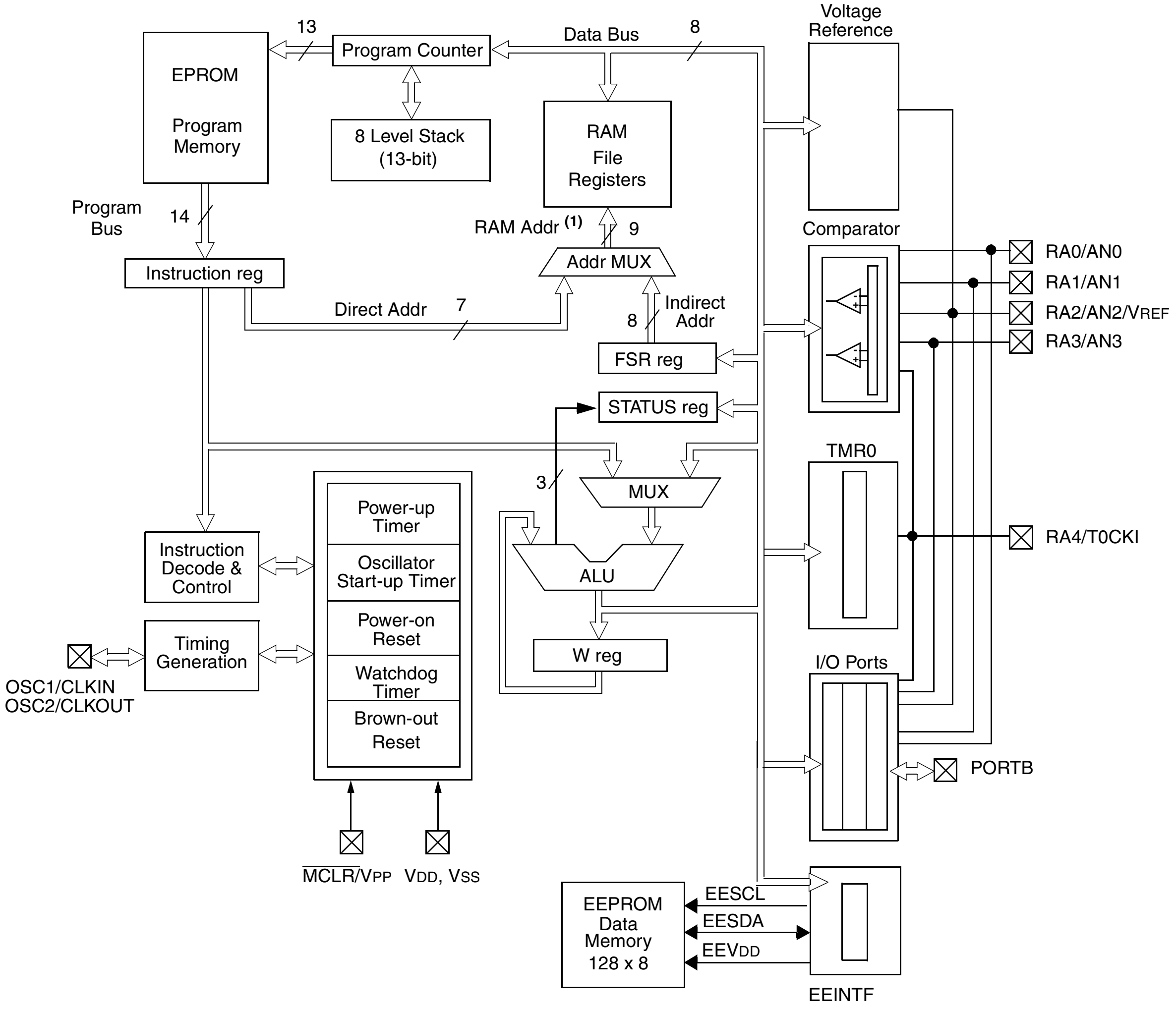
The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a $\overline{\text{Borrow}}$ and $\overline{\text{Digit}}$ $\overline{\text{Borrow}}$ out bit respectively, bit in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

A simplified block diagram is shown in Figure 3-1, with a description of the device pins in Table 3-1.

FIGURE 3-1: BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)	EEPROM DATA MEMORY
PIC16CE623	512 x 14	96 x 8	128 x 8
PIC16CE624	1K x 14	96 x 8	128 x 8
PIC16CE625	2K x 14	128 x 8	128 x 8



Note 1: Higher order bits are from the STATUS register.

5.2 PORTB and TRISB Registers

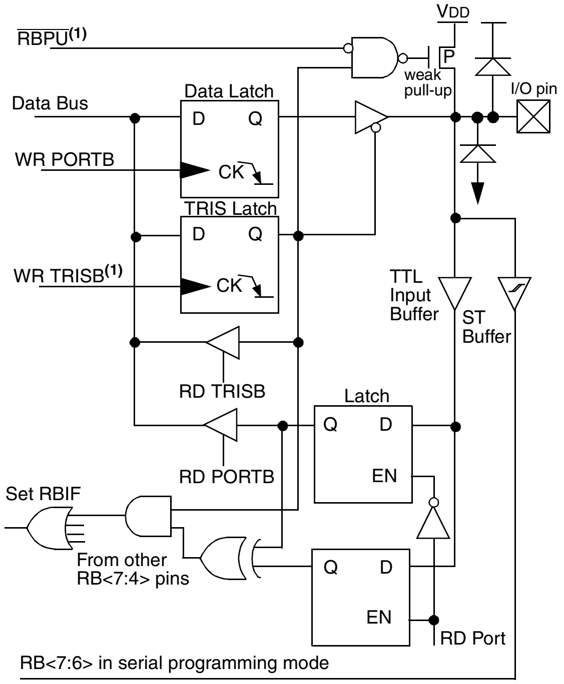
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up (≈200 μA typical). A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{\text{RBPU}}$ (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins of RB<7:4> are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

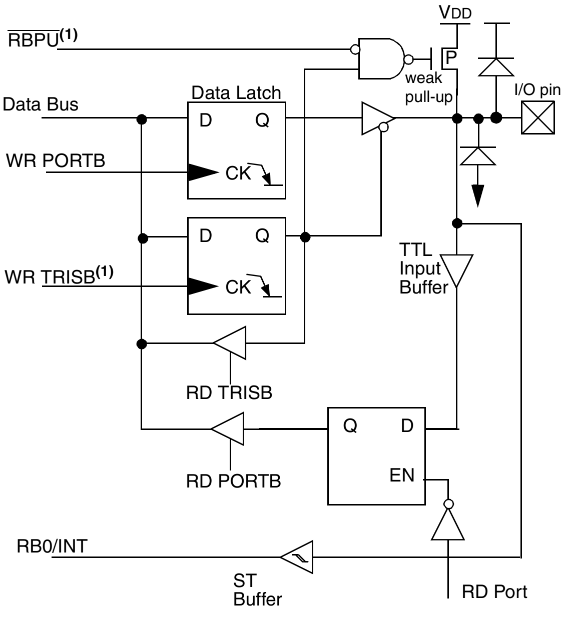
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes".)

> **Note:** If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The `BCF` and `BSF` instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a `BSF` operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the `BSF` operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (i.e., `BCF, BSF`, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (i.e., `BCF, BSF`, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

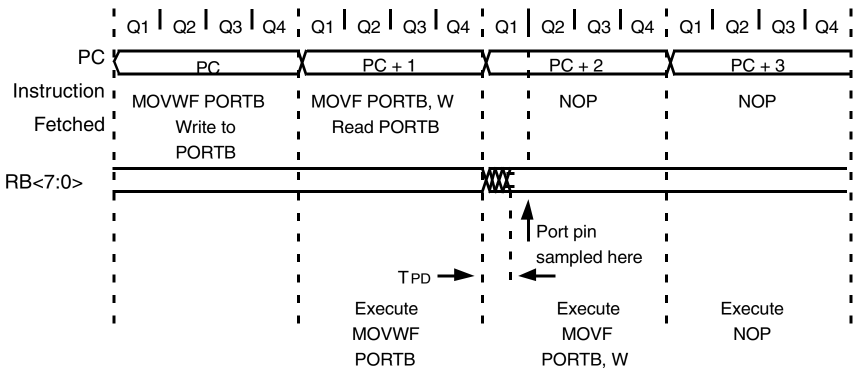
```
; Initial PORT settings:  PORTB<7:4> Inputs
;
;                         PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                         PORT latch  PORT pins
;                         ----------  ----------

    BCF PORTB, 7         ; 01pp pppp   11pp pppp
    BCF PORTB, 6         ; 10pp pppp   11pp pppp
    BSF STATUS,RP0       ;
    BCF TRISB, 7         ; 10pp pppp   11pp pppp
    BCF TRISB, 6         ; 10pp pppp   10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with an NOP or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



Note:

This example shows write to PORTB followed by a read from PORTB.

Note that:

data setup time = (0.25 T_{CY} - T_{PD})
where T_{CY} = instruction cycle and
T_{PD} = propagation delay of Q1 cycle to output valid.

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

TABLE 8-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	`00-- 0000`	`00-- 0000`
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	`000- 0000`	`000- 0000`
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	`-0-- ----`	`-0-- ----`
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	`-0-- ----`	`-0-- ----`
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	`---1 1111`	`---1 1111`

Legend: - = Unimplemented, read as "0", `x` = Unknown, `u` = unchanged

10.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 10-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 10-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

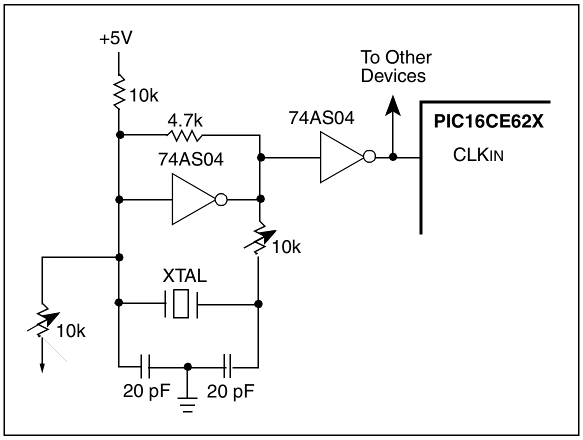
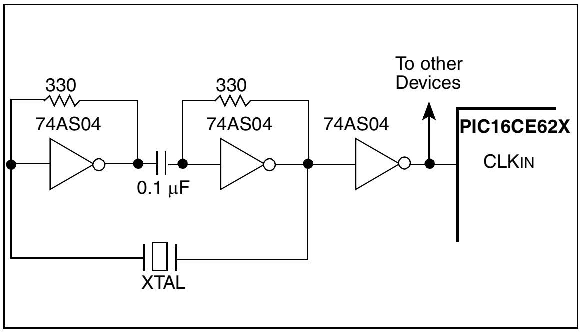


Figure 10-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 10-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



10.2.4 RC OSCILLATOR

For timing insensitive applications the “RC” device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 10-5 shows how the R/C combination is connected to the PIC16CE62X. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (i.e., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 kΩ and 100 kΩ.

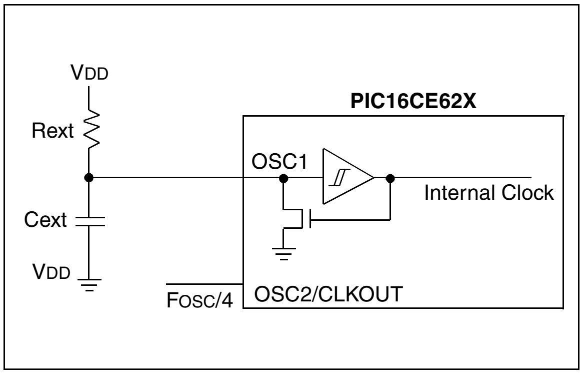
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 14.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 14.0 for variation of oscillator frequency due to VDD for given Rext/Cext values, as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 10-5: RC OSCILLATOR MODE



10.3 Reset

The PIC16CE62X differentiates between various kinds of reset:

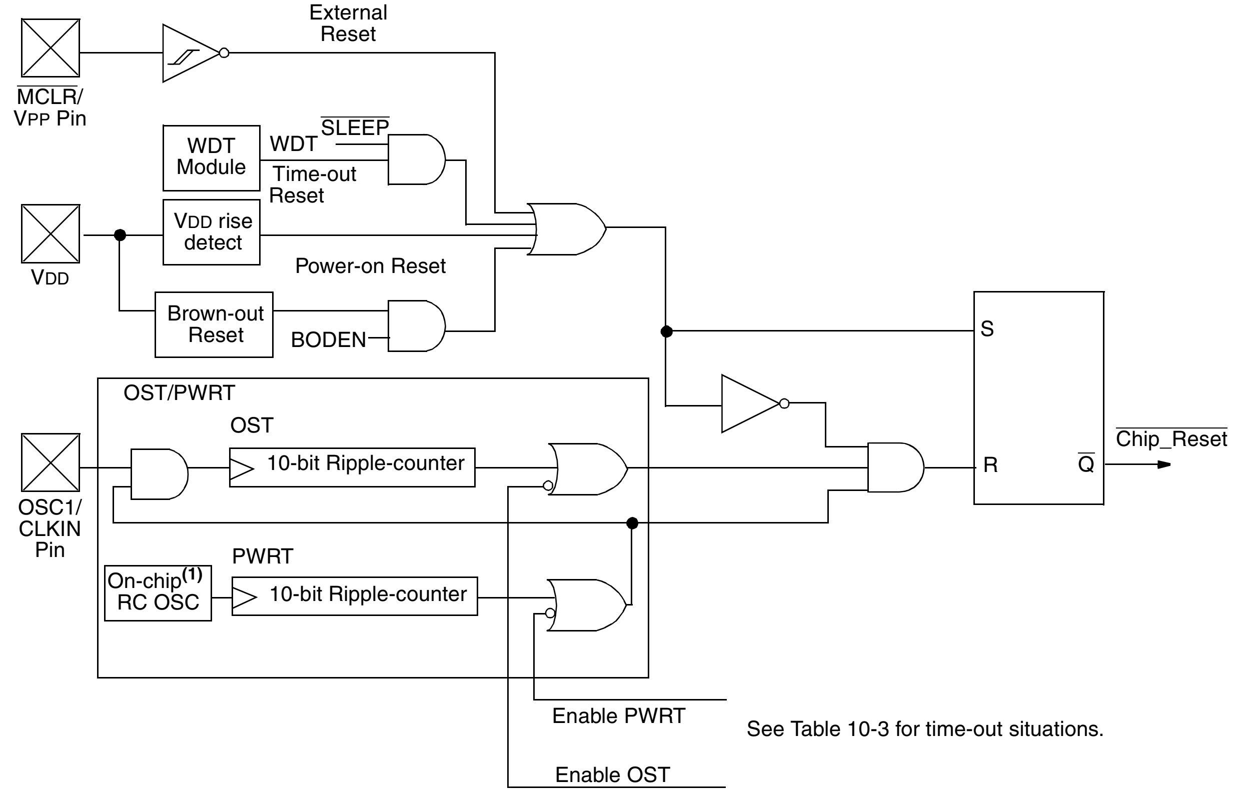
a) Power-on reset (POR)
b) $\overline{\text{MCLR}}$ reset during normal operation
c) $\overline{\text{MCLR}}$ reset during SLEEP
d) WDT reset (normal operation)
e) WDT wake-up (SLEEP)
f) Brown-out Reset (BOD)

Some registers are not affected in any reset condition. Their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a “reset state” on Power-on reset, $\overline{\text{MCLR reset}}$, WDT reset and $\overline{\text{MCLR}}$ reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different reset situations as indicated in Table 10-4. These bits are used in software to determine the nature of the reset. See Table 10-6 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 10-6.

The $\overline{\text{MCLR}}$ reset path has a noise filter to detect and ignore small pulses. See Table 13-5 for pulse width specification.

FIGURE 10-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.

10.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOD)

10.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the $\overline{\text{MCLR}}$ pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See electrical specifications for details.

The POR circuit does not produce an internal reset when VDD declines.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, “Power-up Trouble Shooting”.

10.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, $\overline{\text{PWRTE}}$, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-Up Time delay will vary from chip-to-chip and due to VDD, temperature and process variation. See DC parameters for details.

10.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on power-on reset or wake-up from SLEEP.

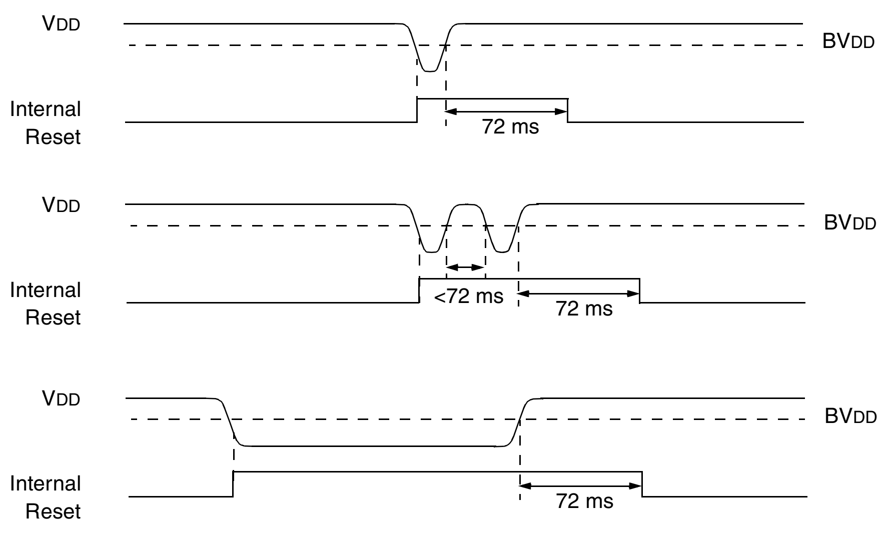
10.4.4 BROWN-OUT RESET (BOD)

The PIC16CE62X members have on-chip Brown-out Reset circuitry. A configuration bit, BOREN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (refer to BVDD parameter D005) for greater than parameter (TBOR) in Table 13-5, the brown-out situation will reset the chip. A reset won’t occur if VDD falls below 4.0V for less than parameter (TBOR).

On any reset (Power-on, Brown-out, Watch-dog, etc.) the chip will remain in reset until VDD rises above BVDD. The Power-up Timer will then be invoked and will keep the chip in reset an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 10-7 shows typical Brown-out situations.

FIGURE 10-7: BROWN-OUT SITUATIONS



11.1 Instruction Descriptions

ADDLW	**Add Literal and W**
Syntax:	[*label*] ADDLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Encoding:	`11` `111x` `kkkk` `kkkk`
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.
Words:	1
Cycles:	1
Example	`ADDLW 0x15` Before Instruction W = 0x10 After Instruction W = 0x25

ADDWF	**Add W and f**
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) + (f) → (dest)
Status Affected:	C, DC, Z
Encoding:	`00` `0111` `dfff` `ffff`
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	`ADDWF FSR, 0` Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0xD9 FSR = 0xC2

ANDLW	**AND Literal with W**
Syntax:	[*label*] ANDLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Encoding:	`11` `1001` `kkkk` `kkkk`
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example	`ANDLW 0x5F` Before Instruction W = 0xA3 After Instruction W = 0x03

ANDWF	**AND W with f**
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) .AND. (f) → (dest)
Status Affected:	Z
Encoding:	`00` `0101` `dfff` `ffff`
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	`ANDWF FSR, 1` Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0x17 FSR = 0x02

SUBLW Subtract W from Literal

Syntax:	[*label*] SUBLW k
Operands:	$0 \le k \le 255$
Operation:	$k - (W) \rightarrow (W)$
Status Affected:	C, DC, Z

Encoding:

`11`	`110x`	`kkkk`	`kkkk`

Description:	The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1

Example 1: `SUBLW 0x02`

Before Instruction

W = 1
C = ?

After Instruction

W = 1
C = 1; result is positive

Example 2: Before Instruction

W = 2
C = ?

After Instruction

W = 0
C = 1; result is zero

Example 3: Before Instruction

W = 3
C = ?

After Instruction

W = 0xFF
C = 0; result is negative

SUBWF Subtract W from f

Syntax:	[*label*] SUBWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(f) - (W) \rightarrow (dest)$
Status Affected:	C, DC, Z

Encoding:

`00`	`0010`	`dfff`	`ffff`

Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.
Words:	1
Cycles:	1

Example 1: `SUBWF REG1,1`

Before Instruction

REG1 = 3
W = 2
C = ?

After Instruction

REG1 = 1
W = 2
C = 1; result is positive

Example 2: Before Instruction

REG1 = 2
W = 2
C = ?

After Instruction

REG1 = 0
W = 2
C = 1; result is zero

Example 3: Before Instruction

REG1 = 1
W = 2
C = ?

After Instruction

REG1 = 0xFF
W = 2
C = 0; result is negative

stand-alone mode the PRO MATE II can read, verify or program PIC devices. It can also set code-protect bits in this mode.

12.11 PICSTART Plus Entry Level Development System

The PICSTART programmer is an easy-to-use, low-cost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

PICSTART Plus supports all PIC devices with up to 40 pins. Larger pin count devices such as the PIC16C92X, and PIC17C76X may be supported with an adapter socket. PICSTART Plus is CE compliant.

12.12 SIMICE Entry-Level Hardware Simulator

SIMICE is an entry-level hardware development system designed to operate in a PC-based environment with Microchip's simulator MPLAB-SIM. Both SIMICE and MPLAB-SIM run under Microchip Technology's MPLAB Integrated Development Environment (IDE) software. Specifically, SIMICE provides hardware simulation for Microchip's PIC12C5XX, PIC12CE5XX, and PIC16C5X families of PIC 8-bit microcontrollers. SIMICE works in conjunction with MPLAB-SIM to provide non-real-time I/O port emulation. SIMICE enables a developer to run simulator code for driving the target system. In addition, the target system can provide input to the simulator code. This capability allows for simple and interactive debugging without having to manually generate MPLAB-SIM stimulus files. SIMICE is a valuable debugging tool for entry-level system development.

12.13 PICDEM-1 Low-Cost PIC MCU Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the MPLAB-ICE emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

12.14 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I^2C bus and separate headers for connection to an LCD module and a keypad.

12.15 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

12.16 PICDEM-17

The PICDEM-17 is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756, PIC17C762, and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included, and the user may erase it and program it with the other sample programs using the PRO MATE II or PICSTART Plus device programmers and easily debug

13.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

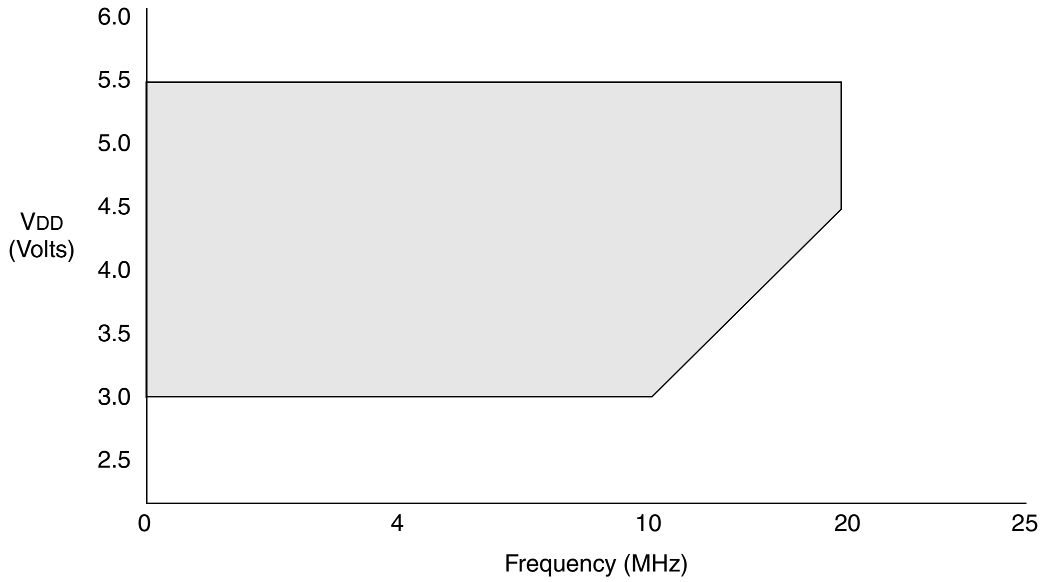
Ambient Temperature under bias	-40° to +125°C
Storage Temperature	-65° to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{\text{MCLR}}$)	-0.6V to V_{DD} +0.6V
Voltage on V_{DD} with respect to V_{SS}	0 to +7.0V
Voltage on RA4 with respect to V_{SS}	8.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V_{SS} (Note 2)	0 to +14V
Voltage on RA4 with respect to V_{SS}	8.5V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of V_{SS} pin	300 mA
Maximum Current into V_{DD} pin	250 mA
Input Clamp Current, I_{IK} (V_I <0 or V_I> V_{DD})	±20 mA
Output Clamp Current, I_{OK} (V_O <0 or V_O>V_{DD})	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	200 mA
Maximum Current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100¾ should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to V_{SS}.

† **NOTICE**: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

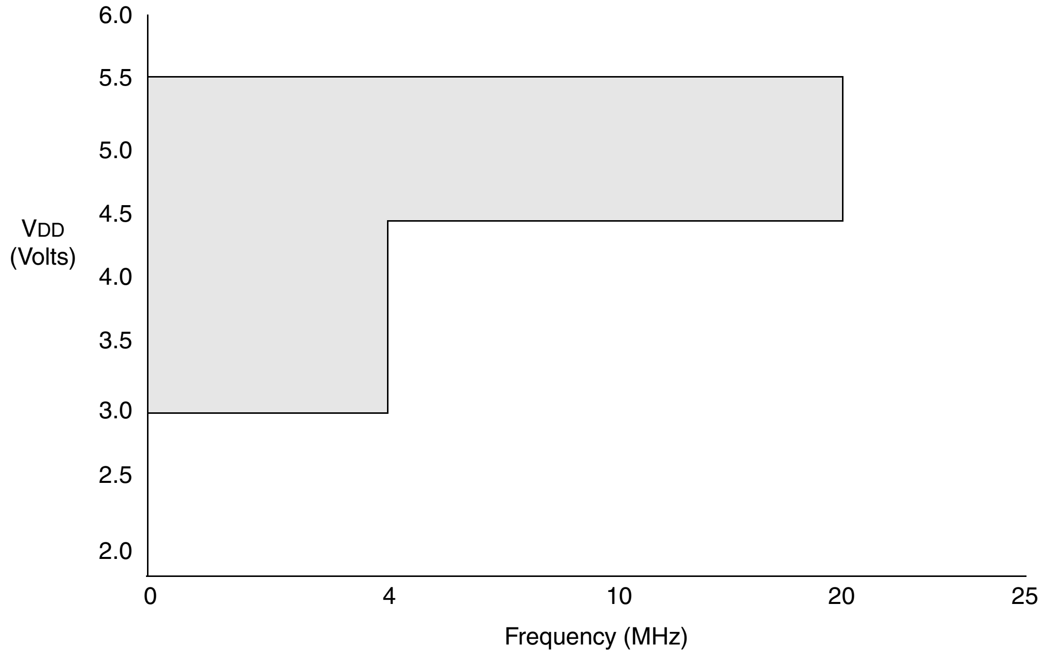
FIGURE 13-1: PIC16CE62X VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 13-2: PIC16CE62X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA < 0°C, +70°C < TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

13.4 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

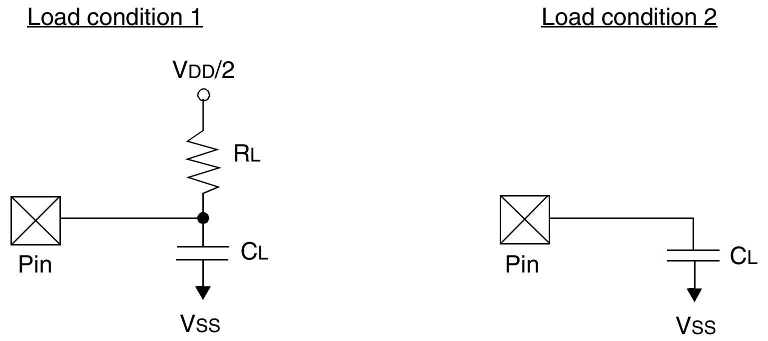
Lowercase subscripts (pp) and their meanings:

pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	$\overline{\text{MCLR}}$		

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 13-4: LOAD CONDITIONS



RL = 464Ω

CL = 50 pF for all pins except OSC2

15 pF for OSC2 output

FIGURE 13-9: TIMER0 CLOCK TIMING

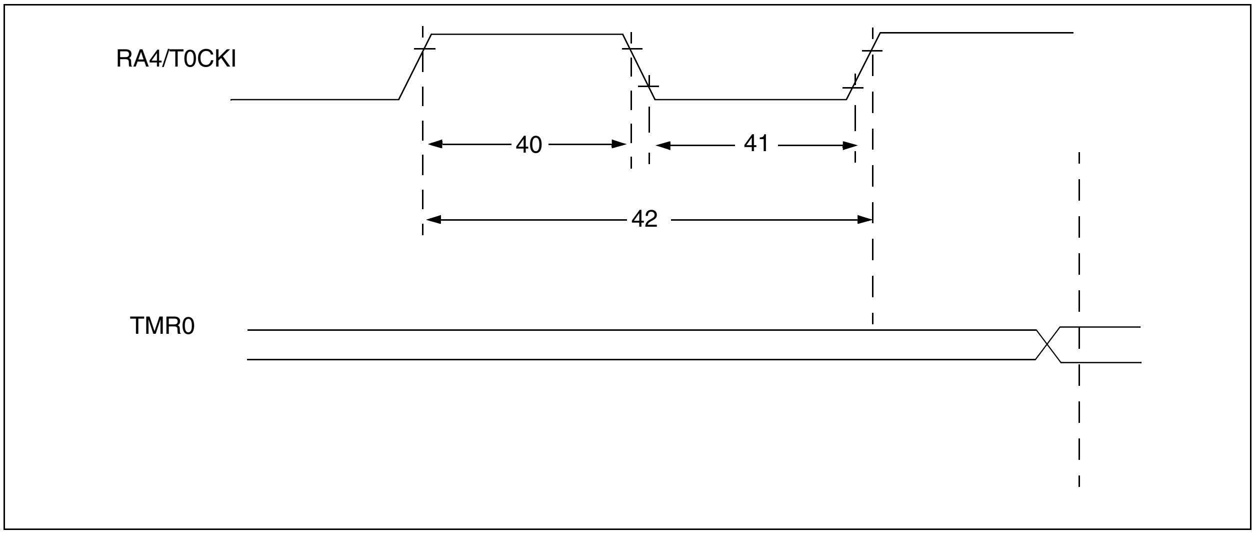


TABLE 13-6: TIMER0 CLOCK REQUIREMENTS

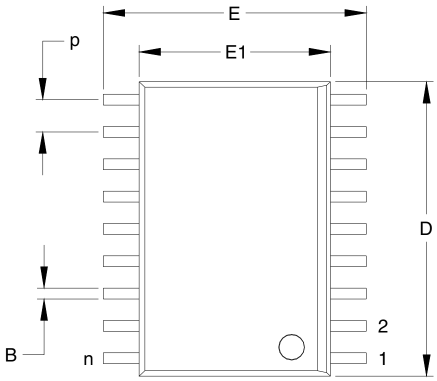
Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$*	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

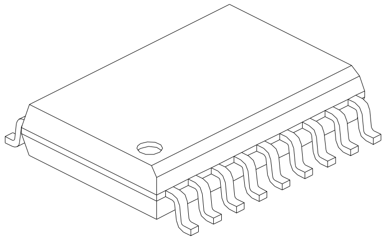
* These parameters are characterized but not tested.

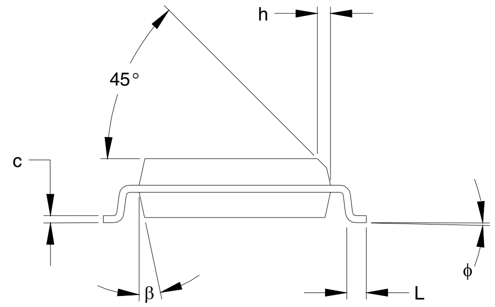
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

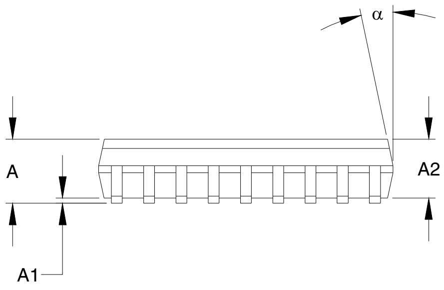
18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

NOTES:

NOTES: